

REMARKS

Claims 1, 3-8, 20, and 22-24 are pending. Claims 2, 9-19, and 21 are herein canceled without prejudice. Claims 1, 6, 20 and 22 are herein amended. Applicants submit that the amendments do not add new material to the current Application. No amendment made is related to the statutory requirements of patentability unless expressly stated herein. No amendment made is for the purpose of narrowing the scope of any claim.

Claims 1, 4, 7, 8, and 20 were rejected; claims 2, 3, 5, and 21-24 were objected to. Claim 6 was not specifically addressed in the office action; however, via telephone calls on November 11, 2005 the Examiner stated that claim 6 was objected.

Drawings

Applicants have modified FIGs. 2-8. Agent for the applicants, Kim-Marie Vo, spoke with the Examiner on November 11, 2005 regarding these proposed drawing changes and the Examiner agreed to them. Applicants submit the no new matter is added.

35 U.S.C. § 103 Rejections**Claims 1 and 3-8**

The Examiner objected to claim 2, which is now rewritten as independent claim 1. Claims 1 and 3-8 are patentable over Osorio under 35 U.S.C. § 103(a) because Osorio fails to teach or suggest all features of claims 1 and 3-8. For example, Osorio fails to teach or suggest, "wherein the conductive layer comprises a ferromagnetic material," as stated in claim 1. For at least this reason, claims 1 and 3-8 are patentable over Osorio under 35 U.S.C. § 103(a).

Claims 20 and 22-24

The Examiner objected to claim 21, which is now rewritten as independent claim 20. Claims 20 and 22-24 are patentable over Osorio under 35 U.S.C. § 103(a) because Osorio fails to teach or suggest all features of claims 20 and 22-24. For example, Osorio fails to teach or suggest, wherein electrically coupling the leadframe to the conductive layer using a wire further comprises providing a wire having a first end and a second end; electrically coupling the first end and the second end of the wire to the semiconductor die; and removing a portion of the mold encapsulant to expose a portion of the wire; and wherein forming a conductive layer further comprises electrically coupling the conductive layer to the wire, which are now features of claim 20. For at least this reason, claims 20 and 22-24 are patentable over Osorio under 35 U.S.C. § 103(a).

Believing to have responded to every issue raised by the Examiner in the last communication mailed, Applicants believe the present Application is currently in a condition of allowance. However, for brevity, simplicity, and to hasten the prosecution process,

rejections of dependent claims may not be addressed if arguments are provided explaining how the independent claims are allowable over all cited prior art or if another reason is given as to why the dependent claim is patentable. Any rejections of dependent claims not addressed are reserved for further discussion.

Applicants earnestly solicit allowance of all pending claims. Please contact Applicant's practitioner listed below if there are any issues.

Respectfully submitted,

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